

## Notice for TAIYO YUDEN products

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Please read this notice before using the TAIYO YUDEN products.

### REMINDERS

- Product information in this catalog is as of October 2016. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual specification.

- Please contact TAIYO YUDEN for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of our products in actual condition of mounting and operating environment before using our products.

- The products listed in this catalog are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC). Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment, disaster prevention equipment, medical equipment, highly public information network equipment including, without limitation, telephone exchange, and base station).

Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment, nuclear control equipment, undersea equipment, military equipment).

When our products are used even for high safety and/or reliability-required devices or circuits of general electronic equipment, it is strongly recommended to perform a thorough safety evaluation prior to use of our products and to install a protection circuit as necessary.

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

- Please note that TAIYO YUDEN shall have no responsibility for any controversies or disputes that may occur in connection with a third party's intellectual property rights and other related rights arising from use of our products. TAIYO YUDEN grants no license for such rights.
- Please note that unless otherwise agreed in writing, the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a fault or defect in our products.
- The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

- Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

# METAL CORE WIRE-WOUND CHIP POWER INDUCTORS(MCOIL™ MA SERIES)



REFLOW

## PARTS NUMBER

\* Operating Temp.: -40~+105°C (Including self-generated heat)

M	A	K	K	2	0	1	6	T	1	R	0	M	△	△
①	②	③	④	⑤	⑥	⑦	⑧							

△=Blank space

### ①Series name

Code	Series name
MA	Metal Core Wire-wound Chip Power Inductor

### ②Dimensions (T)

Code	Dimensions (T) [mm]
KK	1.0
MK	1.2

### ③Dimensions (L × W)

Code	Dimensions (L × W) [mm]
2016	2.0 × 1.6
2520	2.5 × 2.0

### ④Packaging

Code	Packaging
T	Taping

### ⑤Nominal inductance

Code (example)	Nominal inductance [μH]
R47	0.47
1R0	1.0
4R7	4.7

※R=Decimal point

### ⑥Inductance tolerance

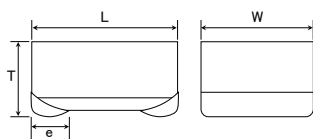
Code	Inductance tolerance
M	±20%

### ⑦Special code

Code	Special code
△	Standard

### ⑧Internal code

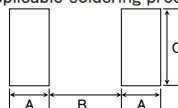
## STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY



### Recommended Land Patterns

#### Surface Mounting

- Mounting and soldering conditions should be checked beforehand.
- Applicable soldering process to these products is reflow soldering only.



Type	A	B	C
2016	0.7	0.8	1.8
2520	0.8	1.2	2.0

Unit: mm

Type	L	W	T	e	Standard quantity [pcs] Taping
MAKK2016	2.0±0.1 (0.079±0.004)	1.6±0.1 (0.063±0.004)	1.0 max (0.039 max)	0.5±0.3 (0.020±0.012)	3000
MAKK2520	2.5±0.2 (0.098±0.008)	2.0±0.2 (0.079±0.008)	1.0 max (0.039 max)	0.5±0.3 (0.020±0.012)	3000
MAMK2520	2.5±0.2 (0.098±0.008)	2.0±0.2 (0.079±0.008)	1.2 max (0.047 max)	0.5±0.3 (0.020±0.012)	3000

Unit: mm (inch)

## ● MAKK2016 type 【Thickness: 1.0mm max.】

Parts number	EHS	Nominal inductance [ $\mu$ H]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance [ $\Omega$ ] (max.)	Rated current ※) [mA] (max.)		Measuring frequency [MHz]
						Saturation current Idc1	Temperature rise current Idc2	
MAKK2016TR24M	RoHS	0.24	±20%	—	0.037	4,200	3,000	2
MAKK2016TR33M	RoHS	0.33	±20%	—	0.040	3,600	3,200	2
MAKK2016TR47M	RoHS	0.47	±20%	—	0.460	3,200	2,800	2
MAKK2016TR68M	RoHS	0.68	±20%	—	0.065	2,500	2,500	2
MAKK2016T1R0M	RoHS	1.0	±20%	—	0.075	2,200	2,200	2
MAKK2016T1R5M	RoHS	1.5	±20%	—	0.130	1,600	1,650	2
MAKK2016T2R2M	RoHS	2.2	±20%	—	0.160	1,500	1,500	2
MAKK2016T3R3M	RoHS	3.3	±20%	—	0.255	1,150	1,200	2
MAKK2016T4R7M	RoHS	4.7	±20%	—	0.380	1,000	950	2

## ● MAKK2520 type 【Thickness: 1.0mm max.】

Parts number	EHS	Nominal inductance [ $\mu$ H]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance [ $\Omega$ ] (max.)	Rated current ※) [mA] (max.)		Measuring frequency [MHz]
						Saturation current Idc1	Temperature rise current Idc2	
MAKK2520TR33M	RoHS	0.33	±20%	—	0.038	4,700	3,500	2
MAKK2520TR47M	RoHS	0.47	±20%	—	0.046	3,900	3,200	2
MAKK2520TR68M	RoHS	0.68	±20%	—	0.059	3,700	2,900	2
MAKK2520T1R0M	RoHS	1.0	±20%	—	0.072	2,700	2,500	2
MAKK2520T1R5M	RoHS	1.5	±20%	—	0.125	2,300	1,800	2
MAKK2520T2R2M	RoHS	2.2	±20%	—	0.156	1,900	1,500	2
MAKK2520T3R3M	RoHS	3.3	±20%	—	0.200	1,550	1,300	2
MAKK2520T4R7M	RoHS	4.7	±20%	—	0.300	1,300	1,100	2

## ● MAMK2520 type 【Thickness: 1.2mm max.】

Parts number	EHS	Nominal inductance [ $\mu$ H]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance [ $\Omega$ ] (max.)	Rated current ※) [mA] (max.)		Measuring frequency [MHz]
						Saturation current Idc1	Temperature rise current Idc2	
MAMK2520TR47M	RoHS	0.47	±20%	—	0.039	4,200	3,400	2
MAMK2520TR68M	RoHS	0.68	±20%	—	0.048	3,200	3,200	2
MAMK2520T1R0M	RoHS	1.0	±20%	—	0.059	3,100	2,700	2
MAMK2520T2R2M	RoHS	2.2	±20%	—	0.110	2,000	1,900	2
MAMK2520T3R3M	RoHS	3.3	±20%	—	0.156	1,800	1,700	2
MAMK2520T4R7M	RoHS	4.7	±20%	—	0.260	1,500	1,300	2

※) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)

※) The temperature rise current value (Idc2) is the DC current value having temperature increase by 40°C. (at 20°C)

※) The rated current value is following either Idc1 or Idc2, which is the lower one.

# METAL CORE WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ MA SERIES / MCOIL™ MA-H SERIES)

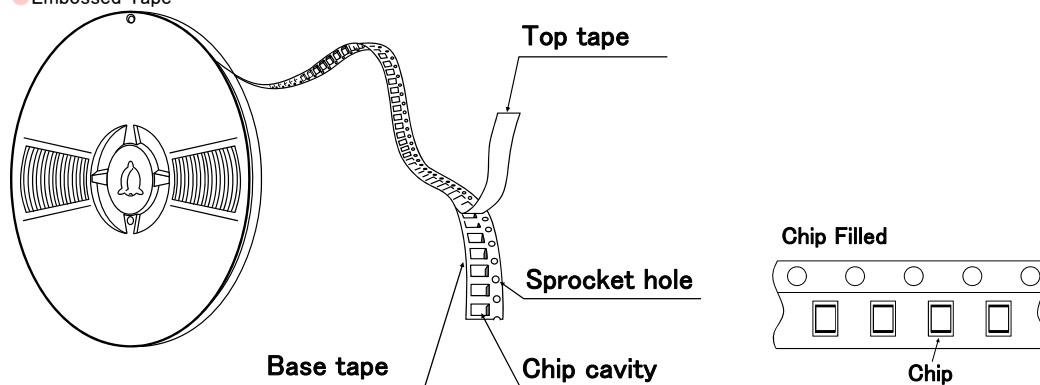
## PACKAGING

### ① Minimum Quantity

Type	Standard Quantity [pcs]
	Tape & Reel
MAKK2016	3000
MAKK2520	3000
MAMK2520	3000

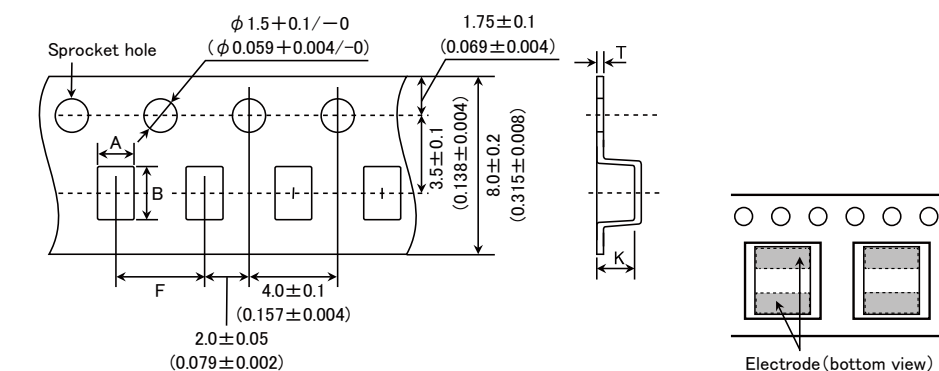
### ② Tape Material

#### ● Embossed Tape



### ③ Taping dimensions

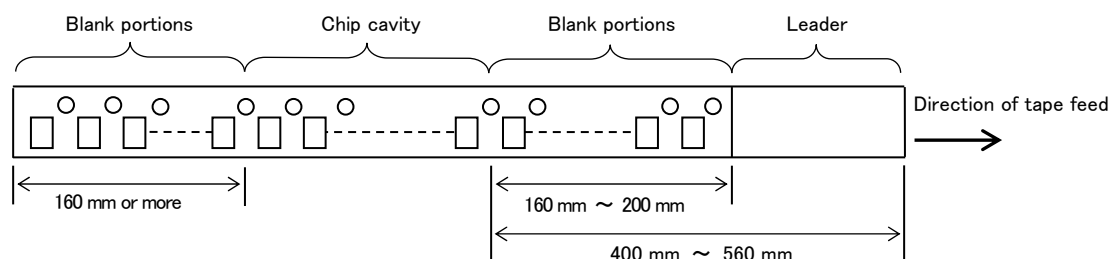
#### ● Embossed tape 8mm wide (0.315 inches wide)



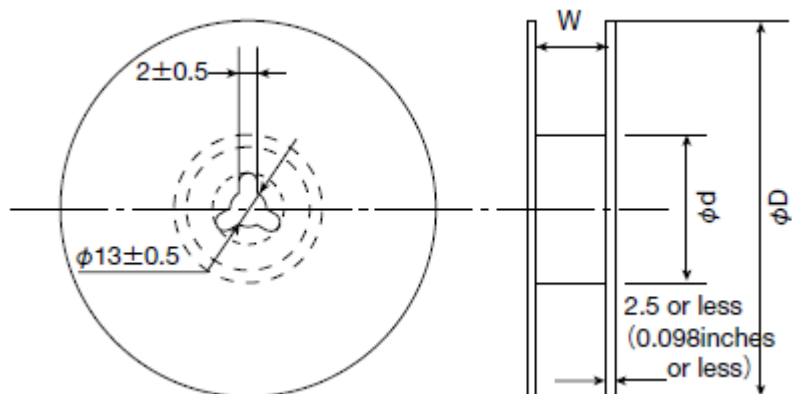
Type	Chip cavity		Insertion pitch	Tape thickness	
	A	B	F	T	K
MAKK2016	1.9 ± 0.1 (0.075 ± 0.004)	2.3 ± 0.1 (0.091 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	0.25 ± 0.05 (0.009 ± 0.002)	1.2 max (0.047 max)
MAKK2520	2.3 ± 0.1 (0.091 ± 0.004)	2.8 ± 0.1 (0.110 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	0.3 ± 0.05 (0.012 ± 0.002)	1.25 max (0.049 max)
MAMK2520	2.3 ± 0.1 (0.091 ± 0.004)	2.8 ± 0.1 (0.110 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	0.3 ± 0.05 (0.012 ± 0.002)	1.4 max (0.055 max)

Unit: mm (inch)

### ④ Leader and Blank portion



## ⑤ Reel size

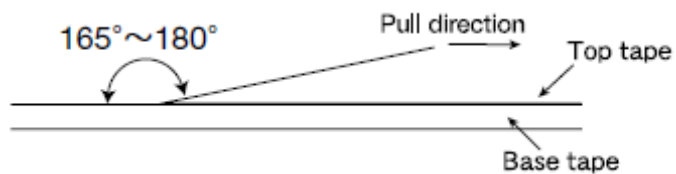


Type	Reel size (Reference values)		
	$\phi D$	$\phi d$	W
MAKK2016	180+0/-3 (7.087+0/-0.118)	60+1/-0 (2.36+0.039/0)	10.0±1.5 (0.394±0.059)
MAKK2520			
MAMK2520			

Unit: mm (inch)

## ⑥ Top Tape Strength

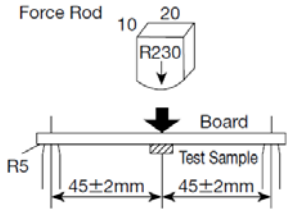
The top tape requires a peel-off force of 0.1 to 1.2N in the direction of the arrow as illustrated below.

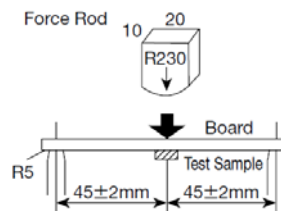


# METAL CORE WIRE-WOUND CHIP POWER INDUCTORS

## (MCOIL™ MA SERIES / MCOIL™ MA-H SERIES)

### RELIABILITY DATA

1. Operating Temperature Range		
Specified Value	MA series	−40~+105℃
	MA-H series	−40~+125℃
Test Methods and Remarks	Including self-generated heat	
2. Storage Temperature Range		
Specified Value	MA series	−40~+85℃
	MA-H series	
Test Methods and Remarks	0 to 40℃ for the product with taping.	
3. Rated current		
Specified Value	MA series	Within the specified tolerance
	MA-H series	
4. Inductance		
Specified Value	MA series	Within the specified tolerance
	MA-H series	
Test Methods and Remarks	Measuring equipment : LCR Meter (HP 4285A or equivalent) Measuring frequency : 2MHz、1V	
5. DC Resistance		
Specified Value	MA series	Within the specified tolerance
	MA-H series	
Test Methods and Remarks	Measuring equipment : DC ohmmeter (HIOKI 3227 or equivalent)	
6. Self resonance frequency		
Specified Value	MA series	—
	MA-H series	
7. Temperature characteristic		
Specified Value	MA series	Inductance change : Within ±15%
	MA-H series	
Test Methods and Remarks	Measurement of inductance shall be taken at temperature range within −40℃~+85℃. With reference to inductance value at +20℃., change rate shall be calculated.	
8. Resistance to flexure of substrate		
Specified Value	MA series	No damage
	MA-H series	
Test Methods and Remarks	<div>The test samples shall be soldered to the test board by the reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm.</div> <div>Test board size : 100×40×1.0 mm</div> <div>Test board material : Glass epoxy-resin</div> <div>Solder cream thickness : 0.12 mm</div> <div></div>	



▶ This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification.  
 For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (<http://www.ty-top.com/>) .

9. Insulation resistance : between wires				
Specified Value	MA series	—		
	MA-H series			
10. Insulation resistance : between wire and core				
Specified Value	MA series	DC25V 100kΩ min		
	MA-H series			
11. Withstanding voltage : between wire and core				
Specified Value	MA series	—		
	MA-H series			
12. Adhesion of terminal electrode				
Specified Value	MA series	No abnormality.		
	MA-H series			
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. Applied force : 10N to X and Y directions. Duration : 5s. Solder cream thickness : 0.12mm.			
13. Resistance to vibration				
Specified Value	MA series	Inductance change : Within ±10% No significant abnormality in appearance.		
	MA-H series			
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions.			
	Frequency Range	10~55Hz		
	Total Amplitude	1.5mm (May not exceed acceleration 196m/s <sup>2</sup> )		
	Sweeping Method	10Hz to 55Hz to 10Hz for 1min.		
	Time	X	For 2 hours on each X, Y, and Z axis.	
		Y		
		Z		
Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.				
14. Solderability				
Specified Value	MA series	At least 90% of surface of terminal electrode is covered by new solder.		
	MA-H series			
Test Methods and Remarks	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table.			
	Flux : Methanol solution containing rosin 25%.			
	Solder Temperature	245±5℃		
	Time	5±0.5 sec.		
※Immersion depth : All sides of mounting terminal shall be immersed.				
15. Resistance to soldering heat				
Specified Value	MA series	Inductance change : Within ±10% No significant abnormality in appearance.		
	MA-H series			
Test Methods and Remarks	The test sample shall be exposed to reflow oven at 230℃ for 40 seconds, with peak temperature at 260+0/—5℃ for 5 seconds, 3 times.			
	Test board material : Glass epoxy-resin			
	Test board thickness : 1.0mm			
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			

16. Thermal shock			
Specified Value	MA series	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
	MA-H series		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.		
	Conditions of 1 cycle		
	Step	Temperature ( $^{\circ}\text{C}$ )	Duration (min)
	1	$-40\pm 3$	$30\pm 3$
	2	Room temperature	Within 3
	3	$+85\pm 2$	$30\pm 3$
	4	Room temperature	Within 3
Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			
17. Damp heat			
Specified Value	MA series	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
	MA-H series		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow.		
	The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.		
	Temperature	$60\pm 2^{\circ}\text{C}$	
	Humidity	$90\sim 95\%\text{RH}$	
	Time	$500+24/-0$ hour	
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.		
18. Loading under damp heat			
Specified Value	MA series	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
	MA-H series		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow.		
	The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table.		
	Temperature	$60\pm 2^{\circ}\text{C}$	
	Humidity	$90\sim 95\%\text{RH}$	
	Applied current	Rated current	
	Time	$500+24/-0$ hour	
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.		
19. Low temperature life test			
Specified Value	MA series	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
	MA-H series		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.		
	Temperature	$-40\pm 2^{\circ}\text{C}$	
	Time	$500+24/-0$ hour	
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.		
20. High temperature life test			
Specified Value	MA series	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.	
	MA-H series		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.		
	Temperature	$85\pm 2^{\circ}\text{C}$	
	Time	$500+24/-0$ hour	
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.		
21. Loading at high temperature life test			
Specified Value	MA series	—	
	MA-H series		



22. Standard condition		
Specified Value	MA series	Standard test condition : Unless otherwise specified, temperature is $20 \pm 15^{\circ}\text{C}$ and $65 \pm 20\%$ of relative humidity. When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of $20 \pm 2^{\circ}\text{C}$ of temperature, $65 \pm 5\%$ relative humidity. Inductance is in accordance with our measured value.
	MA-H series	

# METAL CORE WIRE-WOUND CHIP POWER INDUCTORS

## (MCOIL™ MA SERIES / MCOIL™ MA-H SERIES)

### ■ PRECAUTIONS

#### 1. Circuit Design

Precautions	<p>◆Operating environment</p> <p>1. The products described in this specification are intended for use in general electronic equipment,(office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.</p>
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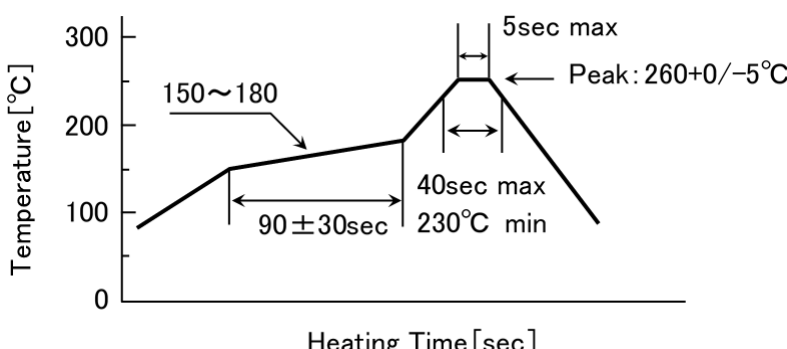
#### 2. PCB Design

Precautions	<p>◆Land pattern design</p> <p>1. Please refer to a recommended land pattern.</p>
Technical considerations	<p>◆Land pattern design</p> <p>Surface Mounting</p> <ul style="list-style-type: none"> <li>• Mounting and soldering conditions should be checked beforehand.</li> <li>• Applicable soldering process to this products is reflow soldering only.</li> </ul>

#### 3. Considerations for automatic placement

Precautions	<p>◆Adjustment of mounting machine</p> <p>1. Excessive impact load should not be imposed on the products when mounting onto the PC boards.</p> <p>2. Mounting and soldering conditions should be checked beforehand.</p>
Technical considerations	<p>◆Adjustment of mounting machine</p> <p>1. When installing products, care should be taken not to apply distortion stress as it may deform the products.</p>

#### 4. Soldering

Precautions	<p>◆Reflow soldering</p> <p>1. Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified.</p> <p>2. The product shall be used reflow soldering only.</p> <p>3. Please do not add any stress to a product until it returns in normal temperature after reflow soldering.</p> <p>◆Lead free soldering</p> <p>1. When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, soldering etc sufficiently.</p>
Technical considerations	<p>◆Reflow soldering</p> <p>1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.</p> <p>Recommended reflow condition (Pb free solder)</p>  <p>Temperature [°C]</p> <p>Heating Time [sec]</p> <p>150~180</p> <p>90±30sec</p> <p>40sec max</p> <p>230°C min</p> <p>5sec max</p> <p>Peak: 260+0/-5°C</p>

#### 5. Cleaning

Precautions	<p>◆Cleaning conditions</p> <p>1. Washing by supersonic waves shall be avoided.</p>
Technical considerations	<p>◆Cleaning conditions</p> <p>1. If washed by supersonic waves, the products might be broken.</p>

6. Handling	
Precautions	<ul style="list-style-type: none"> <li>◆ Handling               <ol style="list-style-type: none"> <li>1. Keep the product away from all magnets and magnetic objects.</li> </ol> </li> <li>◆ Breakaway PC boards (splitting along perforations)               <ol style="list-style-type: none"> <li>1. When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board.</li> <li>2. Board separation should not be done manually, but by using the appropriate devices.</li> </ol> </li> <li>◆ Mechanical considerations               <ol style="list-style-type: none"> <li>1. Please do not give the product any excessive mechanical shocks.</li> <li>2. Please do not add any shock and power to a product in transportation.</li> </ol> </li> <li>◆ Pick-up pressure               <ol style="list-style-type: none"> <li>1. Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part.</li> </ol> </li> <li>◆ Packing               <ol style="list-style-type: none"> <li>1. Please avoid accumulation of a packing box as much as possible.</li> </ol> </li> </ul>
Technical considerations	<ul style="list-style-type: none"> <li>◆ Handling               <ol style="list-style-type: none"> <li>1. There is a case that a characteristic varies with magnetic influence.</li> </ol> </li> <li>◆ Breakaway PC boards (splitting along perforations)               <ol style="list-style-type: none"> <li>1. The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs.</li> </ol> </li> <li>◆ Mechanical considerations               <ol style="list-style-type: none"> <li>1. There is a case to be damaged by a mechanical shock.</li> <li>2. There is a case to be broken by the handling in transportation.</li> </ol> </li> <li>◆ Pick-up pressure               <ol style="list-style-type: none"> <li>1. Damage and a characteristic can vary with an excessive shock or stress.</li> </ol> </li> <li>◆ Packing               <ol style="list-style-type: none"> <li>1. If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products.</li> </ol> </li> </ul>
7. Storage conditions	
Precautions	<ul style="list-style-type: none"> <li>◆ Storage               <ol style="list-style-type: none"> <li>1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.                   <ul style="list-style-type: none"> <li>▪ Recommended conditions                       <ul style="list-style-type: none"> <li>Ambient temperature : 0~40°C</li> <li>Humidity : Below 70% RH</li> </ul> </li> <li>▪ The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes.</li> </ul> </li> </ol> </li> </ul> <p style="margin-left: 40px;">For this reason, product should be used within 6 months from the time of delivery.</p> <p style="margin-left: 40px;">In case of storage over 6 months, solderability shall be checked before actual usage.</p>
Technical considerations	<ul style="list-style-type: none"> <li>◆ Storage               <ol style="list-style-type: none"> <li>1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.</li> </ol> </li> </ul>

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